| L Number | Hits | Search Text | DB | Time stamp |
|---|---|---|---|---|
| 7 | 12 | processor and package and substrate and solder near resist and mold$3 near compound | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:44 |
| 8 | 24 | ("4426341" \| "4437229" \| "4510673" \| "4554126" \| "4585931" \| "4787143" \| "5172053" \| "5175425" \| "5181097" \| "5197650" \| "5256578" \| "5645787" \| "5654204" \| "5872398" \| "5998243" \| "6001672" \| "6021380" \| "6052798" \| "6090644" \| "6106259" \| "6111324" \| "6117382" \| "6192457" \| "6415977" \| "2001/0004002").PN. | USPAT | 2004/07/22 11:02 |
| 9 | 29 | ("5030113" \| "5044912" \| "5101322" \| "5133118" \| "5241133" \| "5261593" \| "5276418" \| "5328087" \| "5349500" \| "5428190" \| "5445308" \| "5502889" \| "5556293" \| "5572405" \| "5611705" \| "5614443" \| "5615477" \| "5620928" \| "5635671" \| "5637916" \| "5652185" \| "5661088" \| "5663593" \| "5668405" \| "5680746" \| "5681757" \| "5688584" \| "5696027" \| "5696666").PN. | USPAT | 2004/07/22 11:04 |
| 10 | 14 | ("4598337" \| "4688152" \| "4866506" \| "5130889" \| "5239198" \| "5241133" \| "5262351" \| "5287247" \| "5296738" \| "5309322" \| "5384689" \| "5506383" \| "5541450" \| "5631807").PN. | USPAT | 2004/07/22 11:07 |
| 11 | 2 | processor and package and solder near resist and mold$3 near compound and (438/901; 29/843 ; 29/844 ; 165/80.3 ; 165/185 ; 174/16.3 ; 174/252 ; 174/258 ; 174/260 ; 257/675 ; 257/676 ; 257/705-707 ; 361/386, 361/401 ; 361/389 ; 361/421 ; 361/403 ; 361/408 ; 361/410 ; 361/414 ; 361/400 ; 361/702 ; 361/704 ; 361/707 ; 361/709 ; 361/723 ; 361/760 ; 361/762 ; 361/767 ; 361/778).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:20 |
| 12 | 5 | ("5389497" \| "5500315" \| "5903041" \| "6137634" \| "6207346").PN. | USPAT | 2004/07/22 11:18 |
| 13 | 3 | processor and package and solder near resist and mold$3 near compound and (174/255; 174/260 ; 361/748-751).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:22 |

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| 14 | 5 | Manepalli near Rahul .inv. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:21 |
|---|---|---|---|---|
| 15 | 232 | Jiang near Tongbi .inv. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:22 |
| 16 | 232 | Jiang near Tongbi .inv. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:42 |
| 17 | 0 | Jiang near Tongbi .inv.     and processor near IC | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:42 |
| 18 | 0 | Jiang near Tongbi .inv.  and integrate adj circuit near package | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:43 |
| 19 | 0 | Jiang near Tongbi .inv.  and integrate adj package | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:44 |
| 20 | 168 | Jiang near Tongbi .inv.  and  package | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:44 |
| 21 | 23 | method near (processor or package) and substrate and solder near resist and mold$3 near compound | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:46 |
| 22 | 0 | "method for making package" and substrate and solder near resist and mold$3 near compound | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:46 |
| 23 | 0 | "method for making package" and solder near resist and mold$3 near compound | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:46 |

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| 24 | 27 | IC and solder near resist and mold$3 near compound | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:48 |
|---|---|---|---|---|
| 25 | 6 | IC and solder near resist and mold$3 near compound and (29/840; 29/841 ; 29/832 ; 257/668 ; 257/778 ; 257/676        ; 438/118 ; 438/126 ; 438/336 ; 438/200 ; 174/255 ; 174/260).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:48 |
| 26 | 6 | IC and solder near resist and mold$3 near compound and (29/840; 29/841 ; 29/832 ; 257/668 ; 257/778 ; 257/676 ; 438/118 ; 438/126 ; 438/336 ; 438/200 ; 174/255 ; 174/260).ccls. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/07/22 11:48 |
| 27 | 12 | ("5701013" | "5712707" | "5757507" | "5789118" | "5953128" | "5976740" | "6023338" | "6031614" | "6048755" | "6063530" | "6068954" | "6441504" | "2002/0020908" | "2002/0148897").PN. | USPAT | 2004/07/22 11:49 |

| | Title | Current OR |
|---|---|---|
| 1 | **Solder resist opening to define a combination pin one indicator and fiducial** | 29/840 |
| 2 | **Solder resist opening to define a combination pin one indicator and fiducial** | 29/841 |
| 3 | **Solder resist opening to define a combination pin one indicator and fiducial** | 174/260 |
| 4 | **Method of making a semiconductor device having an opening in a solder mask** | 29/840 |
| 5 | **Method of production of semiconductor device** | 29/832 |
| 6 | **Method for making a conductive film composite** | 29/846 |

|   | Current XRef | Retrieval Classif |
|---|---|---|
| 1 | 29/832; 29/834; 29/843 | 29/832; 29/840 |
| 2 | 29/834; 29/840; 29/854; 29/855 | 29/840; 29/841 |
| 3 | 29/832; 29/840 | 174/260; 29/832; 29/840 |
| 4 | 174/255; 174/260; 29/832; 29/841 | 174/255; 174/260; 29/832; 29/840; 29/841 |
| 5 | 174/260; 228/179.1; 228/180.21; 257/E21.514; 29/840; 29/846 | 174/260; 29/832; 29/840 |
| 6 | 174/255; 174/261; 29/845 | 174/255 |